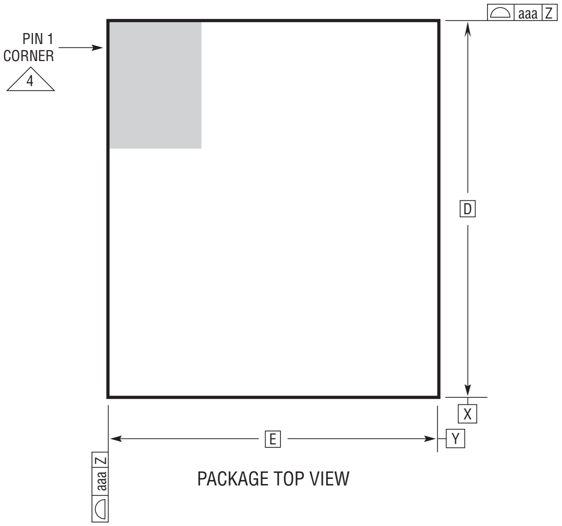
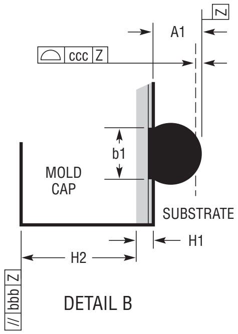
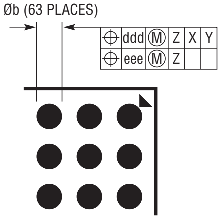
BGA Package
63-Lead (7mm × 8mm × 3.15mm)
(Reference LTC DWG # 05-08-7024 Rev Ø)



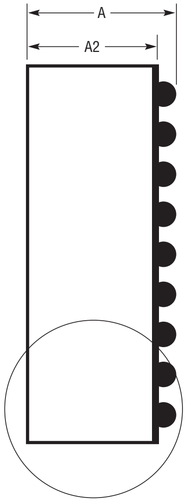
PACKAGE TOP VIEW



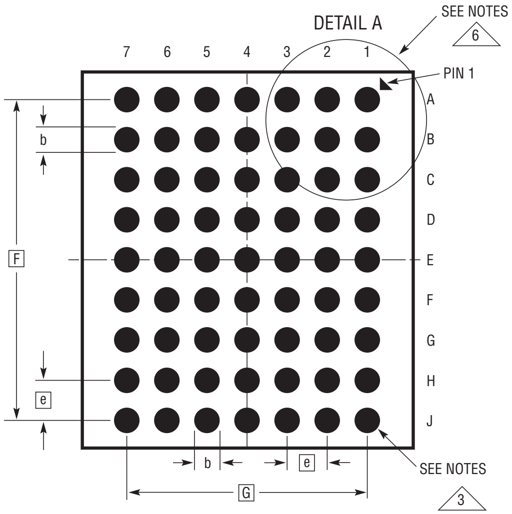
DETAIL B



DETAIL A



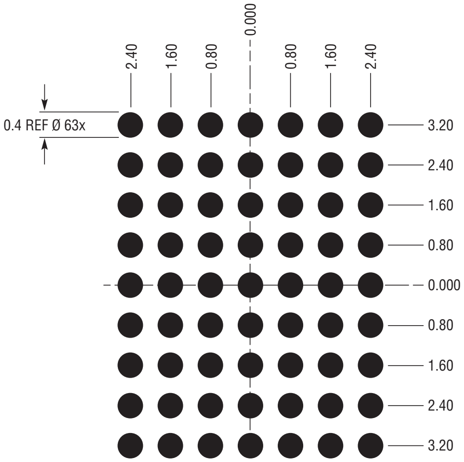
DETAIL B
PACKAGE SIDE VIEW



PACKAGE BOTTOM VIEW

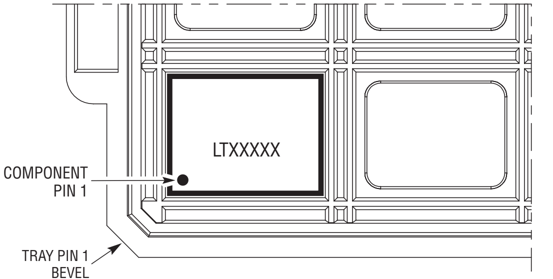
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. ALL DIMENSIONS ARE IN MILLIMETERS
3. BALL DESIGNATION PER JEP95
4. DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN 1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
5. PRIMARY DATUM -Z- IS SEATING PLANE
6. ⚠ PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



SUGGESTED PCB LAYOUT
TOP VIEW

	DIMENSIONS			
SYMBOL	MIN	NOM	MAX	NOTES
A	2.96	3.15	3.34	
A1	0.30	0.40	0.50	BALL HT
A2	2.66	2.75	2.84	
b	0.45	0.50	0.55	BALL DIMENSION
b1	0.37	0.40	0.43	PAD DIMENSION
D		8.00		
E		7.00		
e		0.80		
F		6.40		
G		4.80		
H1		0.25 REF		SUBSTRATE THK
H2		2.50 REF		MOLD CAP HT
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.15	
eee			0.08	



PACKAGE IN TRAY LOADING ORIENTATION

BGA 63 0120 REV Ø